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BURN-IN SCREENING METHOD OF ELEC-
TRONIC PART

Abstract

PROBLEM TO BE SOLVED: To perform a reliable screening of semiconductor wafers by a method wherein a burn-in device of high flatness is equipped with a burn-in base unit of high flatness, a flexible reusable Z-axial member unit, and a wafer level contact sheet unit is used.

SOLUTION: A burn-in device comprises a burn-in base unit 7 equipped with a base of high flatness, a flexible reusable Z-axial member unit 8 which contains elastomer as required, a wafer level contact sheet unit 9 laminated on the Z-axial member unit 8, and its assembly. The flexible reusable Z-axial member unit 8 is arranged between the burn-in base unit 7 and the wafer level contact sheet 9, and they can be electrically connected together. Therefore, a reliable screening of a semiconductor wafer can be performed.

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